

APPROVAL SHEET

To :

Customer P/N :

UDE P/N : SB20-ZZ-0002

Description : SFP28 Cage 1X2

Press-fit

Without Lightpipe

Packing With Hard Tray

SFP28 25G(NRZ), SFP56 50G(PAM4)



Spec No.
SB2021004-00

Update Date
2021/5/31

Revision
A

Approved	Checked	Prepared



湧德電子 股份有限公司
UDE Corp.

桃園市(33852) 蘆竹區內溪路 68 巷13號

No.13, Ln. 68, Neixi Rd., Luzhu Dist., Taoyuan City (33852), Taiwan

TEL: 886-3-3242000 FAX: 886-3-3246611

<http://www.ude-corp.com/>

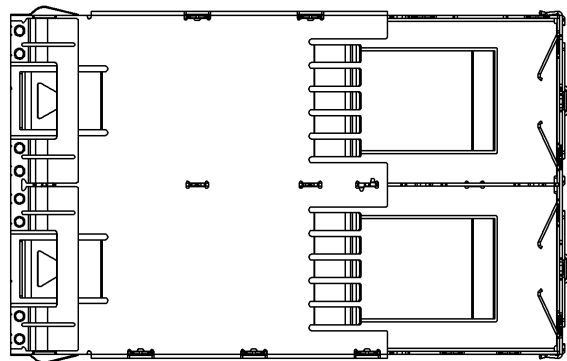
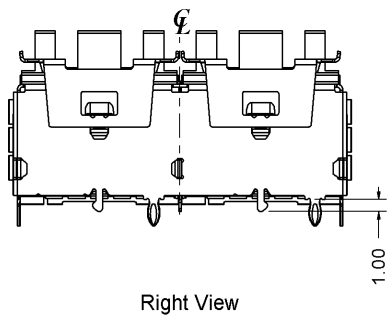
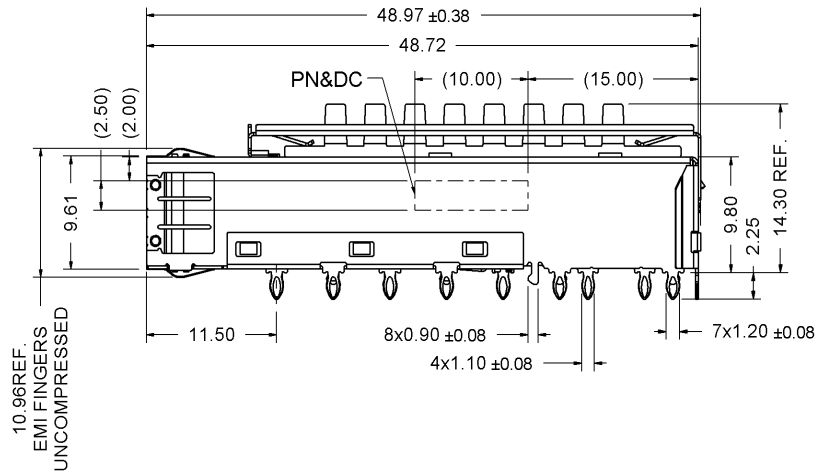
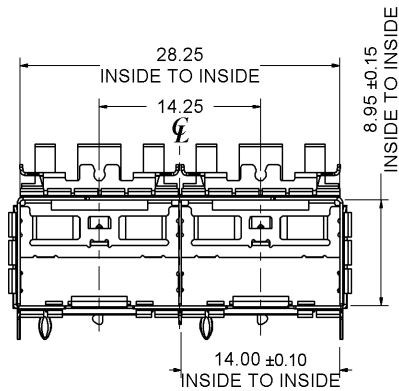
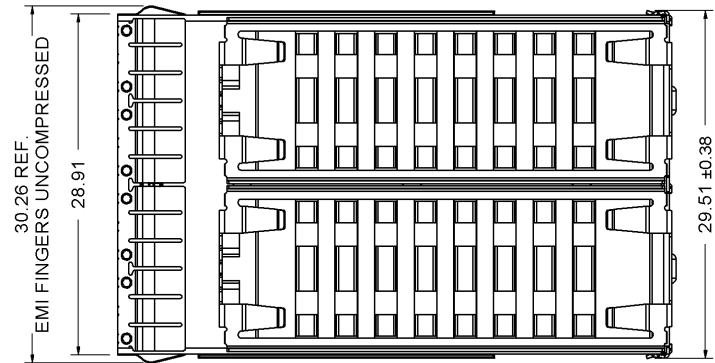
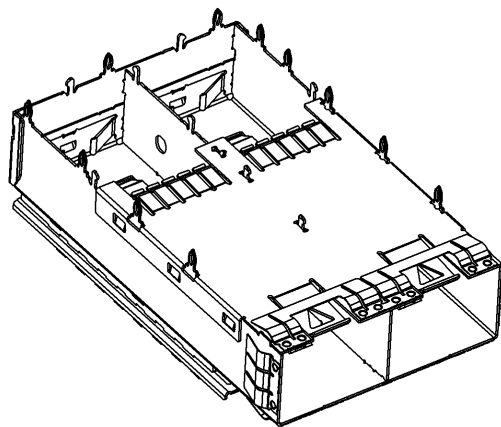
Revision History

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1. MECHANICAL DIMENSION

Product Dimension

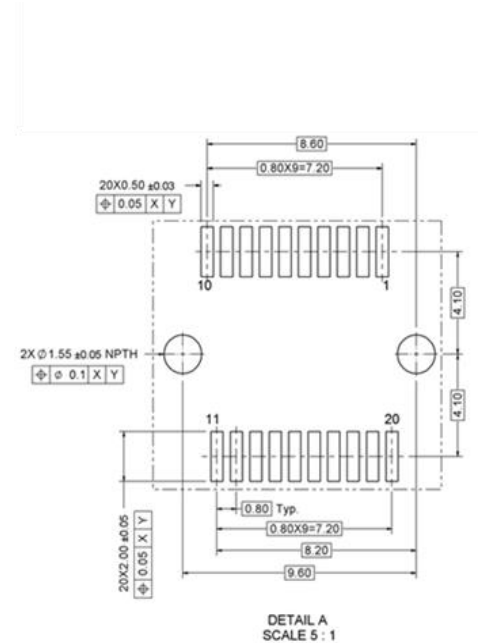
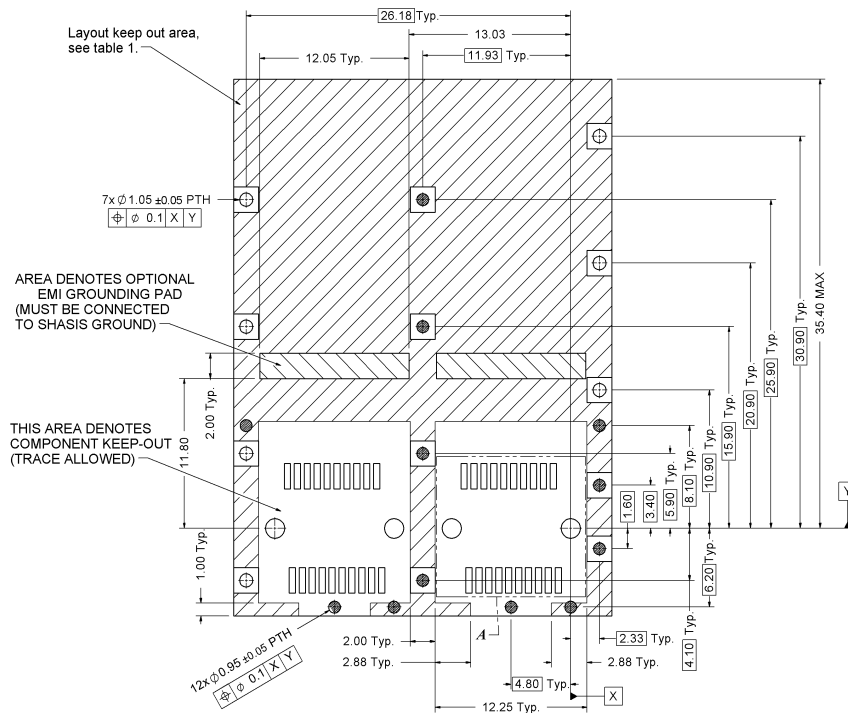
Unit:mm	X.X : ± 0.38
	X.XX : ± 0.20



2. Recommended PCB Layout.Component Side of Board

All dimension units are "mm".

All dimension tolerances are $\pm 0.05\text{mm}$ unless otherwise specified



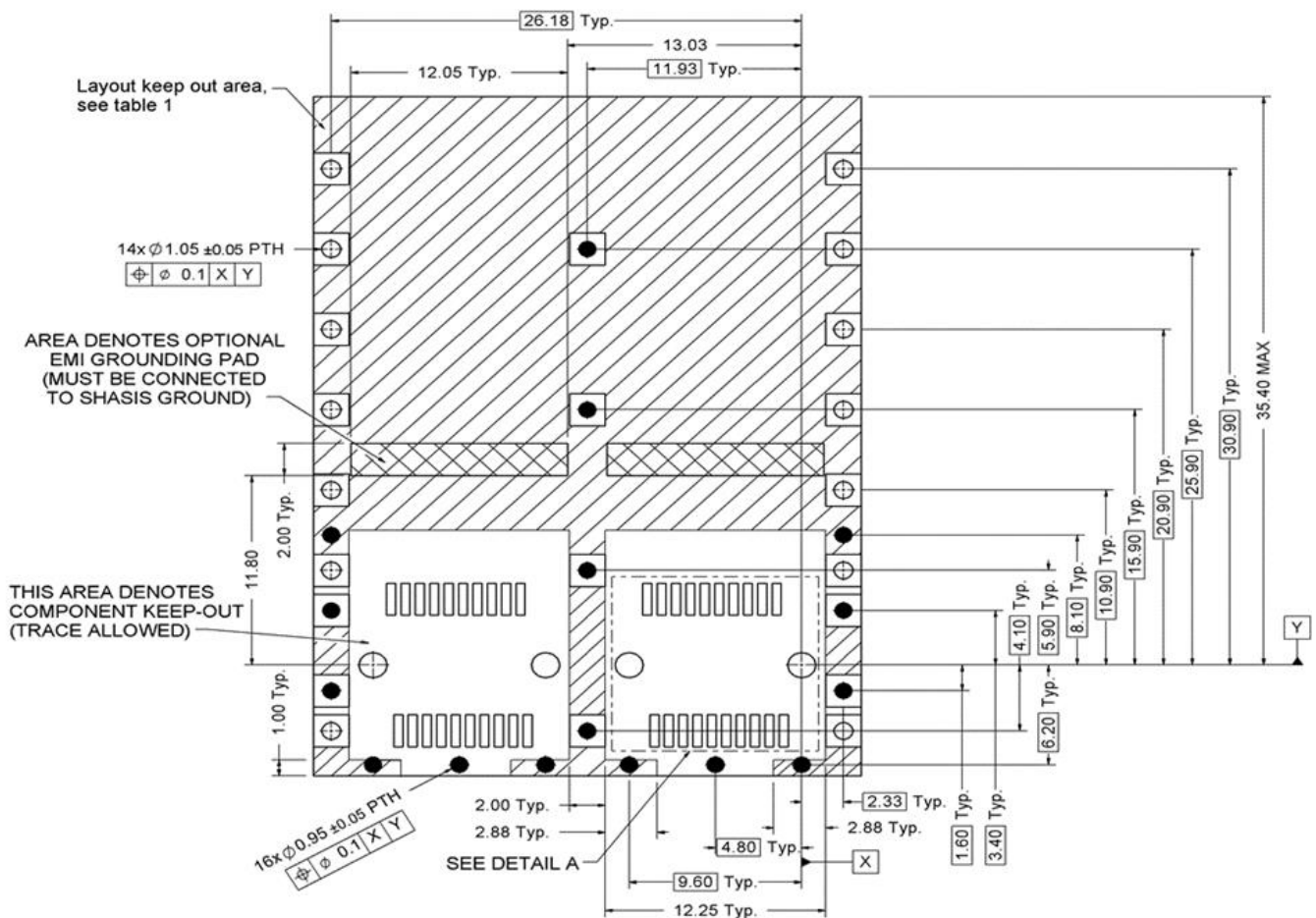
NOTES:

- 1.PADS AND VIAS CONNECT TO CHASSIS GROUND
RECOMMEND PADS TO BE 2.00mm SQUARE
- 2.RECOMMENDED THRU HOLE PLATING INCLUDES
HASL,OSP,OR IMMERSION(GOLD,SILVER,OR TIN)
- 3.1.57mm MINIMUM PCB THICKNESS FOR SINGLE SIDED USE.

Table1

Layout Layer	Trace	component	Grounding	Test Point	Via Hole	PTH	NPTH
Component side	X	X	O	X	X	X	O
Inner layer	O	NA	O	NA	O	X	O
Bottom side	O	O	O	O	O	X	O

X--Forbid; O--OK; NA--Not Applicable.

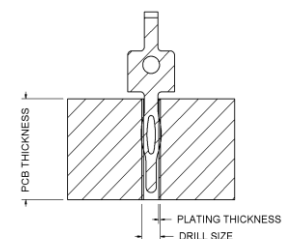


NOTES:

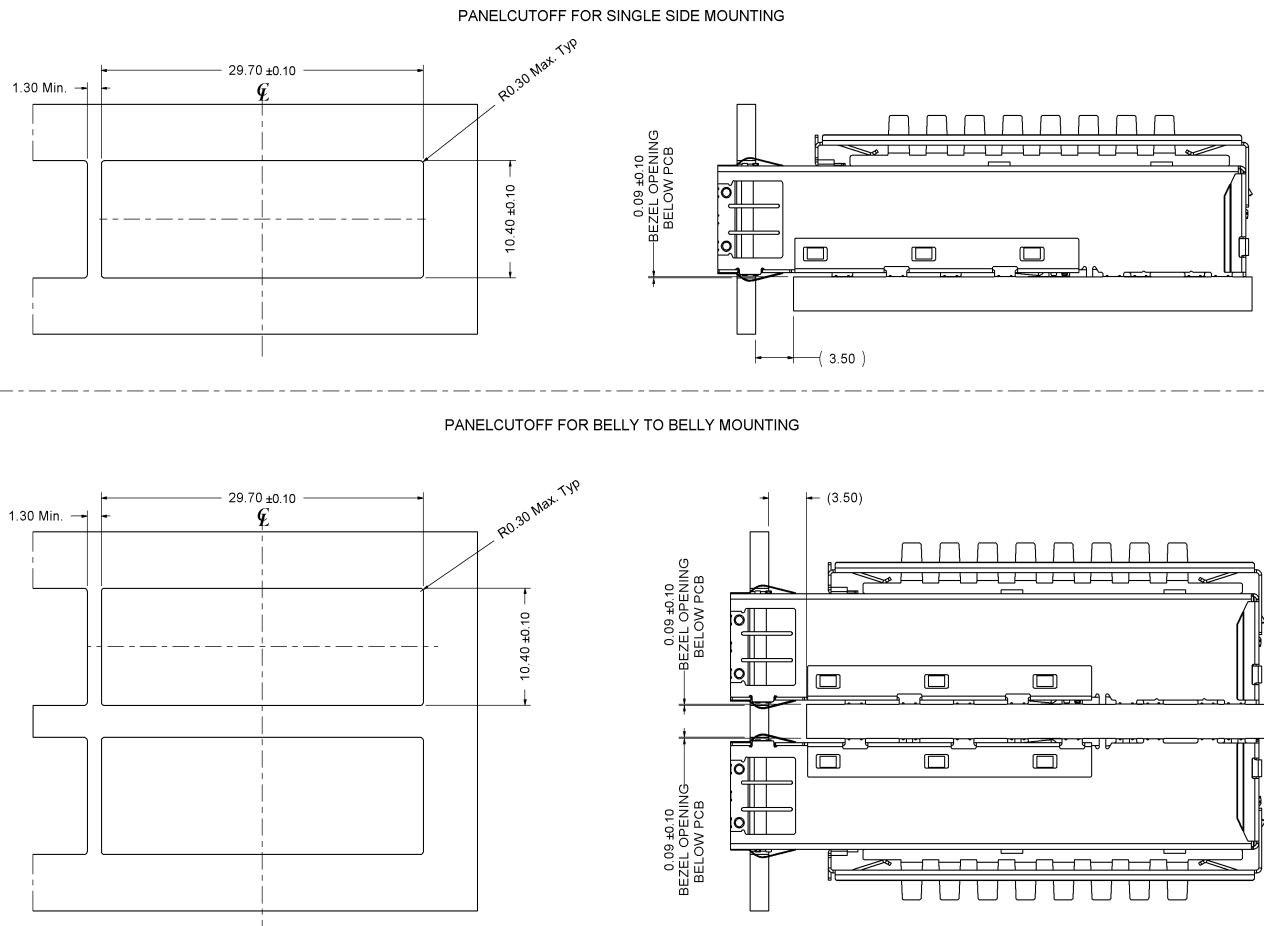
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RECOMMEND PADS TO BE 2.00mm SQUARE
- 2.RECOMMENDED THRU HOLE PLATING INCLUDES
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- 3.3.00mm MINIMUM PCB THICKNESS FOR BELLY TO BELLY SIDED USE.

RECOMMENDED MOTHER BOARD THROUGH HOLE DIMENSION

PLATED THROUGH HOLE	1.05 SHIELD PINS	0.95 SHIELD PINS
FINISHED HOLE DIAMETER	1.05±0.05	0.95±0.05
DRILLED HOLE DIAMETER	1.15	1.05
COPPER PLATING	0.025	0.025



3. Recommended Panel cutout



PRESS-FIT ASSEMBLIES
Hand place using proper seating force to engage all Leg tails into plated thru-holes.

Assemblies are to be seated per the instructions associated with the appropriate insertion tool
Note:UDE recommends only one connector assembly be installed at a time.

ASSEMBLE INSERTION FORCE		
PORT SIZE	PCB FINISH	FORCE
1X2	Copper w/OSP	190±20N

4. Packing Information

- 16 pcs finished goods per tray
- 7 trays(112pcs finished goods) per master carton

5. REQUIREMENTS

Design and Construction

Product shall be of design, construction and physical dimensions specified on applicable.

Material

Shield Parts

Top Shell : Copper Alloy, Thickness=0.25mm

Finish : 30 μ " min. Nickel

Bottom Shell : Copper Alloy, Thickness=0.25mm

Finish : 30 μ " min. Nickel

Mid Ground : Copper Alloy, Thickness=0.25mm

Finish : 30 μ " min. Nickel

Inner Spring : SUS304, Thickness=0.20mm

Finish : 30 μ " min. Nickel

EMI Spring Finger : Ph.Bronze, Thickness=0.08mm

Finish : 30 μ " min. Nickel

Heatsink Clip: Stainless steel, Thickness=0.25mm

Heatsink: Aluminum Alloy

Finish : Anodic oxidation, Natural Colour

6. Operating and Storage Temperature

Operating Temperature : -40°C to +85°C

Storage Temperature : - 55°C+105°C

7. SFP CAGE specifications

Insertion force: 18 N max at a max. rate of 25.4mm per minute

(SFP module to SFP cage)(Without Heatsink)

Extraction force : 12.5 N max at a max. rate of 25.4mm per minute

(SFP module to SFP cage)(Without Heatsink)

Cage Retention (Latch strength) : 90N Min.

Durability : 100 cycles for standard class

8. Performance and Test Description

Product is designed to meet electrical, mechanical and environmental performance requirements specified in below table.

All tests are performed at ambient environmental conditions per MIL-STD-1344A and EIA-364 unless otherwise specified.

9. Packaging and Packing

All parts shall be packaged and packed to protect against physical damage, corrosion and deterioration during shipment and storage.